



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Michitaka Urushima

Serial No.: 09/839,298

Group Art Unit: 2829

Filed: April 23, 2001

Examiner: Geyer, Scott B.

For: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SAME

Honorable Commissioner of Patents
Washington, D.C. 20231

AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated October 31, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

B Please cancel claim 27 without prejudice or disclaimer.

Please amend claims 5 and 30 as follows:

- 5.** (Twice Amended) A semiconductor device comprising:
- a semiconductor chip;
 - an adhesive layer formed on a surface of said semiconductor chip on which an electrode is formed;
 - a bump provided on said electrode of said semiconductor chip and projecting from a surface of said adhesive layer;

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